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PRODUCT	NO. OF CONTACTS	DIM A	DIM B	DIM C	DIM D	DIM E	DIM F		DIM	G	CONT, PLATI NOTE	NG	HOLD-DOWN			ESSING AP	G	
91294-001	120	1.930/50.95	.830/21.08	.725/18.42	1.550/39.37	2.150/54.61	1.790/45.	.47	.965/2	4.51	30 (GXT	t			APS		
-002	160	2.430/61.72	1.080/.27.43	.975/24.76	2.050/52.07	2.650/67.31	2.290/58.	.16	1.215/	30.86	30 (GXT				ALLED N		
	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.790/70.	.87	1.465/	37.21	- 30 (SXT	OPTION SEE		CONN	ONNECTOR		
-033	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.790/70.	.87	1.465/	37.21	30 (GXT	NOTE 6	6	NOT S ON COI	HIPPED NNECTOR	PED ECTOR	
91294-413	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.790/70.	.87	1.465/	37.21	60 (GXT			CAPS S LOOS	SUPPLIED E PIECE		

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LEAD FREE OPTION;

91294-001LF		120	1.930/50.95	.830/21.08	.725/18.42	1.550/39.37	2.150/54.61	1.790/45.47	.965/24.51	30 GXT	t	CAPS
	-002LF	160	2.430/61.72	1.080/.27.43	.975/24.76	2.050/52.07	2.650/67.31	2.290/58.16	1.215/30.86	30 GXT		INSTALLED ON
	-003LF	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.790/70.87	1.465/37.21	30 GXT	OPTIONAL SEE	CONNECTOR
	-033LF	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.790/70.87	1.465/37.21	30 GXT	NOTE 6	NOT SHIPPED ON CONNECTOR
9129	4-413LF	200	2.930/74.42	1.330/33.78	1.225/31.12	2.550/64.77	3.150/80.01	2.790/70.87	1.465/37.21	60 GXT		CAPS SUPPLIED LOOSE PIECE

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1 MATERIALS:

DIELECTRIC: LCP CONTACTS: PHOS BRONZE FRAME: ZINC ALLOY #3

2 PLATING:

SOLDER TAILS: 150 u"/3.81um Sn-Pb FRAME: 100u "/2.54um NICKEL CONTACTS: 30u"/0.76um GXT OVER 50u"/1.27um Ni OR 60u"/1.52um GXT OVER 75u"/1.90um Ni.

1.

LEAD FREE OPTION: SOLDER TAILS: 150 u"/3.81um Sn FRAME: 100u "/2.54um NICKEL CONTACTS: 30u"/0.76um GXT OVER 50u"/1.27um Ni OR 60u"/1.52um GXT OVER 75u"/1.90um Ni.

- WHEN CONNECTOR IS MATED WITH OPPOSITE HALF, THE PARALLEL BD. TO BD. HGT. IS 0.47 ±0.01. (APPLYS TO VERT. THRU & SURFACE MT. STYLES)
- (4) THE SOLDER TAILS ON THIS PRODUCT ARE DESIGNED TO BE COMPLIANT IN ORDER TO ACCOMMODATE PRINTED CIRCUIT BOARD DIMENSIONAL VARIATIONS. THEREFORE, HOLDDOWN HARDWARE IS REQUIRED TO SECURE THE CONNECTOR TO THE PRINTED CIRCUIT BOARD FOR MOST TYPES OF SOLDER REFLOW OPERATIONS. FOR FURTHER APPLICATION DATA, INCLUDING HOLE SIZES FOR VARIOUS TYPES OF HARDWARE, SEE TA-932.
- 5 DO NOT REMOVE PROCESSING CAP UNTIL SOLDERING IS COMPLETED.
- 6 BY ADDING LETTER "H" TO TABULATED P/N, THE OPTIONAL HOLD-DOWNS WILL BE SUPPLIED INTEGRAL W/CONNECTOR. EXAMPLE: XXXXX-XXXH (HOLD-DOWN)

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7. PART NUMBERS WITH LF SUFFIX AT THE END ARE LEAD FREE.

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8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 20 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.

9. IF "LF" P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008.

10. PRODUCT SPECIFICATION PER BUS-12-105.

tolerance ISO 406 ISO 1101 mat'l. code surface projection product family ISO 1302 🗸 MICROPAX $\odot \lhd$ Itr ecn no dr date tolerances unless otherwise specified title Ρ .XX±.01/0.3 INCH/MM MICROPAX .025M SMT angles linear .xxx±.005/0.13 PLUG DOUBLE MODULE 0°±2' .xxxx±.0020/0.051 scale 1:1 sheet3 of 3 size dr T. HOUTZ 3/04/93 dwg no C engr M. HAHN 3/04/93 294 91 Аз 3/04/93 chr M. HAHN \geq Product Customer Drawing appd M. HAHN 3/04/93 type sheet revision index sheet D 4PDS: Rev :P STATUS:Released Printed: Sep 10, 2013

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